

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant :	Kiyoshi Mita	Art Unit :	2815
Serial No. :	10/813,782	Examiner :	Chris C. Chu
Filed :	March 31, 2004	Conf. No. :	5223
Title :	SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE SAME		

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO ACTION OF APRIL 19, 2007

In reply to the final Office action of April 19, 2007, Applicants submit the following remarks.

Claims 1-3 and 6-16 are pending for further examination.

35 USC § 112 Claim Rejections

Claims 15 and 16 were rejected as indefinite for lack of support in the specification. In particular, the Office action alleged that the specification failed to disclose a semiconductor element “in direct contact” with a first conductive pattern as recited by those claims. As support for this argument, the Office action points to pg. 7, lines 14-16 of the present specification which state that the semiconductor element 13 is “fixed to the mounting substrate 11 with an insulating adhesive interposed therebetween.”

Applicants respectfully disagree with the claim rejections and submit that the Examiner's interpretation is incorrect. Although the specification discloses that an insulating adhesive is interposed between the semiconductor element and substrate, there is no disclosure that the adhesive must be formed between the semiconductor element and the first conductive pattern. Rather, the insulating adhesive also may be formed in the spaces between first conductive patterns 12 (*see* circled region in attached FIG. 1B). In that case, the insulating adhesive does not necessarily prohibit portions of the semiconductor element 13 from “directly” contacting the conductive pattern 12 as shown in FIG. 1B. Accordingly, applicants submit that there is appropriate support for the features recited in pending claims 15 and 16.